-60V Pch +Pch Middle Power MOSFET

V _{DSS}	-60V
R _{DS(on)} (Max.)	70mΩ
I _D	±4.5A
P_D	2.0W

Features

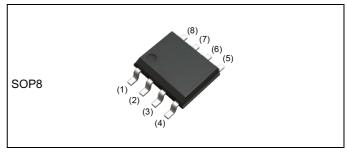
- 1) Low on resistance.
- 2) Small Surface Mount Package (SOP8).
- 3) Pb-free lead plating; RoHS compliant.
- 4) Halogen Free.

Application

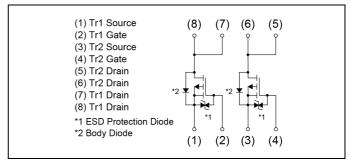
Switching

Motor Drive

Outline



•Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Basic ordering unit (pcs)	2500
	Taping code	ТВ
	Marking	SH8J31

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parame	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	-60	V	
Continuous drain current		I _D	±4.5	Α
Pulsed drain current		I _{DP} *1	±18	А
Gate - Source voltage	V _{GSS}	±20	V	
Avalanche current, single puls	I _{AS} *2	-4.5	А	
Avalanche energy, single puls	se	E _{AS} *2	14	mJ
	total	D *3	2.0	
Power dissipation	element	- P _D *3	1.4	W
	total	P _D *4	1.4	
Junction temperature	T _j	150	°C	
Operating junction and storag	T _{stg}	-55 to +150	°C	

Thermal resistance

Parameter		Cymbol	Values			l leit
		Symbol	Min.	Тур.	Max.	Unit
	total	٦ *3	-	-	62.5	
Thermal resistance, junction - ambient	element	R _{thJA} *3	-	-	89.2	°C/W
	total	R _{thJA} *4	-	-	89.2	

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

D 4		0 111	Values			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = -1mA$	-60	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = -1mA referenced to 25°C	-	-60	-	mV/°C
Zero gate voltage drain current	I _{DSS}	V _{DS} = -60V, V _{GS} = 0V	-	-	-1	μA
Gate - Source leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±10	μA
Gate threshold voltage	V _{GS(th)}	V _{DS} = -10V, I _D = -1mA	-1.0	-	-3.0	V
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$	I _D = -1mA referenced to 25°C	-	3.0	-	mV/°C
		$V_{GS} = -10V, I_D = -4.5A$	-	50	70	
Static drain - source on - state resistance	R _{DS(on)} *5	V _{GS} = -4.5V, I _D = -4.5A	-	55	80	mΩ
		V _{GS} = -4.0V, I _D = -4.5A	-	60	85	
Gate resistance	R_G	f = 1MHz, open drain	-	4.0	-	Ω
Forward Transfer Admittance	Y _{fs} *5	V _{DS} = -10V, I _D = -4.5A	6.5	-	-	S

^{*1} Pw \leq 10 μ s , Duty cycle \leq 1%

^{*2} L \simeq 1mH, V_{DD} = -30V, R_G = 25 Ω , STARTING T_i = 25 $^{\circ}$ C Fig.3-1,3-2

^{*3} Mounted on a ceramic board (30×30×0.8mm)

^{*4} Mounted on a FR4 (25×25×0.8mm)

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Daramatar	Cymahal	Conditions		l leit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	2500	-	
Output capacitance	C _{oss}	V _{DS} = -10V	-	540	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	140	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq -30V, V_{GS} = -10V$	-	17	-	
Rise time	t _r *5	I _D = -2.25A	-	18	-	
Turn - off delay time	t _{d(off)} *5	$R_L = 13.3\Omega$	-	100	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	40	-	

• Gate charge characteristics $(T_a = 25^{\circ}C) < Tr1$ and Tr2 > Tr1

Parameter	Symbol Conditions -		Values			Unit
raianetei			Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}		-	40	-	
Gate - Source charge	Q _{gs} *5	$V_{DD} \simeq -30V, I_{D} = -4.5A$ $V_{GS} = -10V$	-	5.5	-	nC
Gate - Drain charge	Q _{gd} *5	1.00	-	5.0	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Darameter	Cumbal	Conditions	Values			l leit
Parameter	Symbol	Symbol Conditions -		Тур.	Max.	Unit
Continuous forward current	I _S	T - 25°C	-	-	-1.6	^
Pulse forward current	I _{SP} *1	T _a = 25°C	-	-	-18	Α
Forward voltage	V _{SD} *5	V _{GS} = 0V, I _S = -1.6A	-	-	-1.2	V

Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

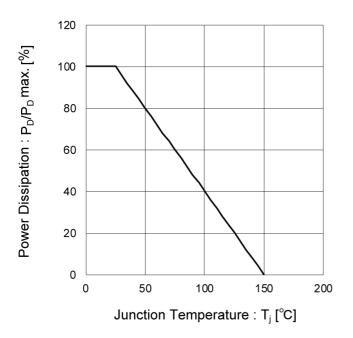
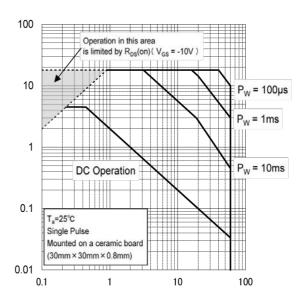


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V_{DS}[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

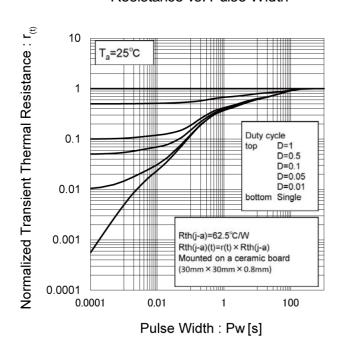
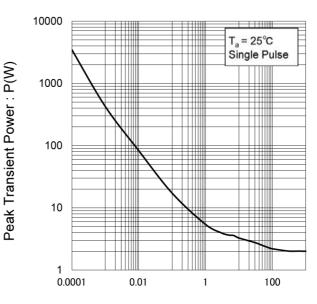


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width: Pw[s]

Drain Current: -l_D [A]

• Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

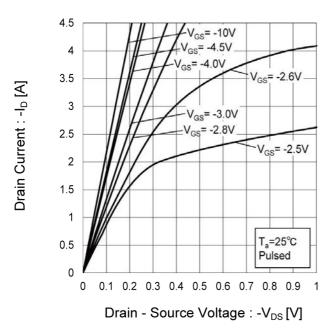
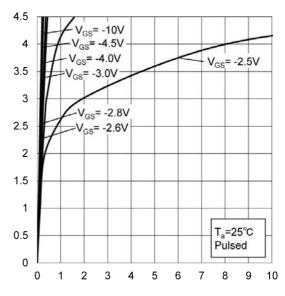


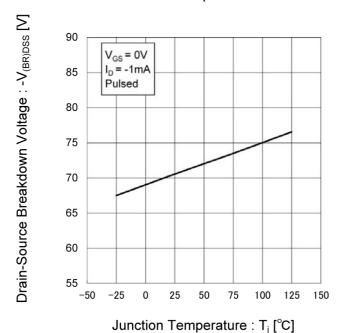
Fig.6 Typical Output Characteristics(II)



Drain - Source Voltage : -V_{DS} [V]

Fig.7 Breakdown Voltage vs.

Junction Temperature



Drain Current : -I_D [A]

• Electrical characteristic curves

Fig.8 Typical Transfer Characteristics

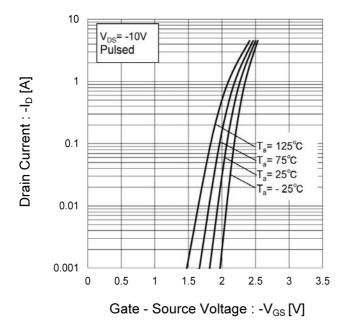


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

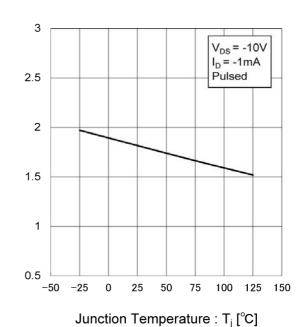
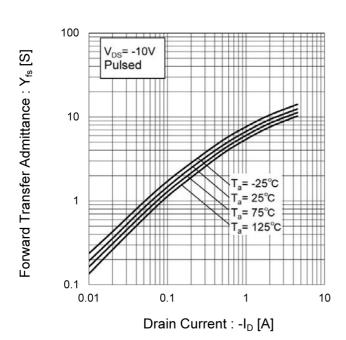


Fig.10 Forward Transfer Admittance vs.
Drain Current



Gate Threshold Voltage: -V_{GS(th)} [V]

SH8J31

• Electrical characteristic curves

Fig.11 Drain Current Derating Curve

Drain Current Dissipation

Orange (%) 80

Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

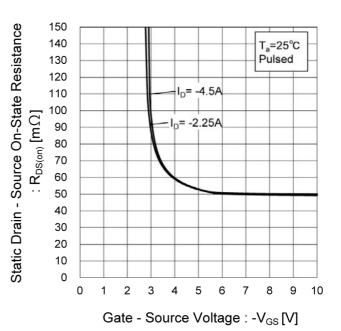
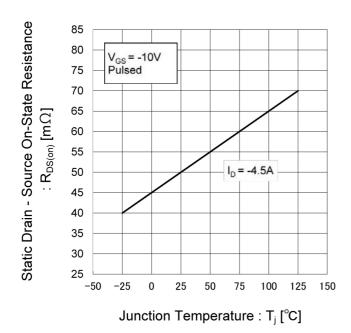


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





SH8J31 Datasheet

• Electrical characteristic curves

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

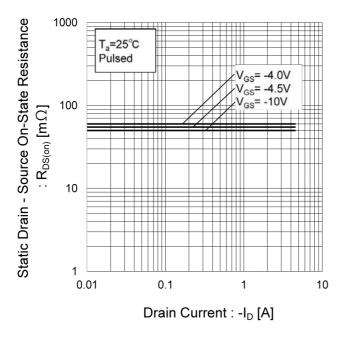


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

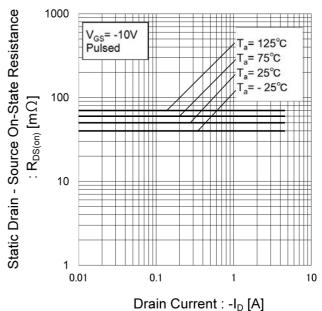


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

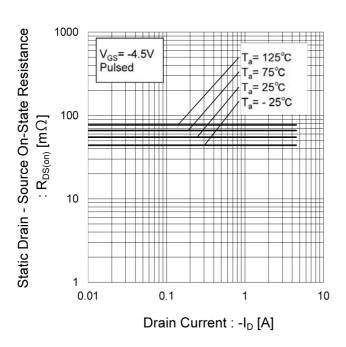
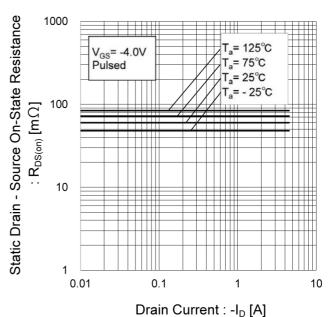


Fig.17 Static Drain - Source On - State
Resistance vs. Drain Current (IV)



• Electrical characteristic curves

Fig.18 Typical Capacitance vs.

Drain - Source Voltage

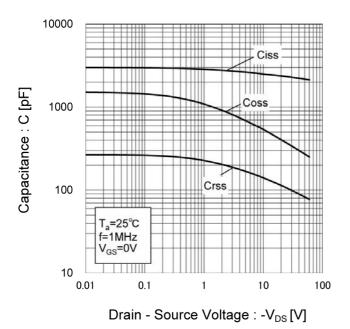


Fig.19 Switching Characteristics

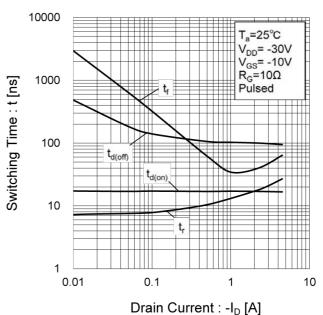


Fig.20 Dynamic Input Characteristics

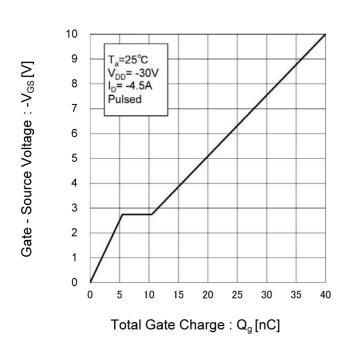
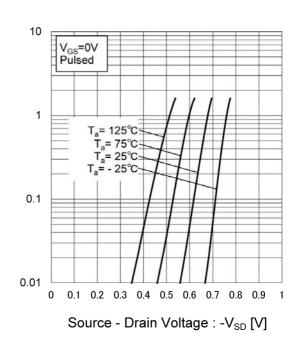


Fig.21 Source Current vs.

Source Drain Voltage



Source Current : -I_s [A]

• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

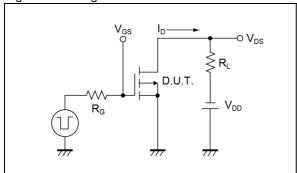


Fig.2-1 Gate Charge Measurement Circuit

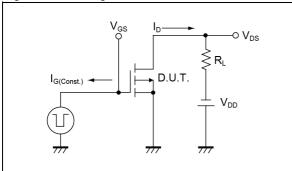


Fig.3-1 Avalanche Measurement Circuit

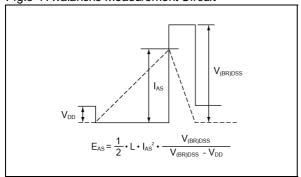


Fig.1-2 Switching Waveforms

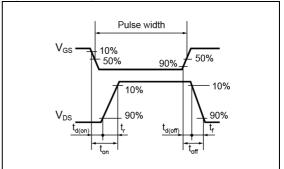


Fig.2-2 Gate Charge Waveform

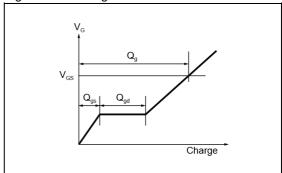
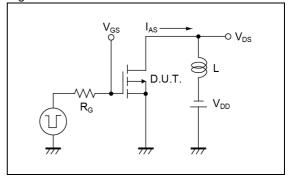
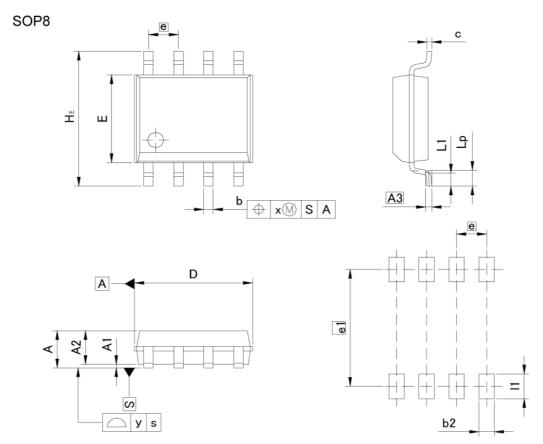


Fig.3-2 Avalanche Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	<u></u>	1.75	=	0.069
A1	0.	15	0.0	06
A2	1.40	1.60	0.055	0.063
A3	0.	25	0.0	10
b	0.30	0.50	0.012	0.020
С	0.10	0.30	0.004	0.012
D	4.80	5.20	0.189	0.205
E	3.75	4.05	0.148	0.159
е	1.	27	0.050	
HE	5.70	6.30	0.224	0.248
L1	0.40	0.60	0.016	0.024
Lp	0.65	0.85	0.026	0.033
х	0.	0.15		06
у	0.	10	0.0	04
DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX

Dimension in mm/inches

b2

e1



0.026

0.045

0.203

0.65

5.15

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Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	CLASSIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSIII

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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QR code printed on ROHM Products label is for ROHM's internal use only.

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SH8J31 - Web Page

Distribution Inventory

Part Number	SH8J31
Package	SOP8
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes

单击下面可查看定价,库存,交付和生命周期等信息

>>ROHM Semiconductor(罗姆)